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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10000020	FILING DATE 12/04/2001	CLASS 438	SUBCLASS 1	GAU 281Z	EXAMINER D. H. ...
**APPLICANTS: Tago Masamoto; Tomita Yoshihiro;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 366539-0000 12/04/2000					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO WNZ-2427	
TITLE : Method for laminating and mounting semiconductor chip					

U.S. DEPT. OF COMM./PAT. & TM.-PTO-435L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	
		Print Claim for O.G.	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		Application Examiner	
		PREPARED FOR ISSUE	
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